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Title: Partnership Opportunity-Heterogeneously Integrated System on a Chip

NAICS code: 334-Compute and Electronic Product Manufacturing; 335-Electrical Equipment, Appliance, and Component Manufacturing; 339-Miscellaneous Manufacturing

Classification code: 59-Electrical and electronic equipment components; 81-Containers, packaging & packing supplies

Body:

Sandia National Laboratories (Sandia) seeks interested parties for commercializing patented technology for packaging and integrating heterogeneous microsystems devices onto a single chip in a cost-effective and efficient manner. The technology is described in US patent 7,335,972. Potential applications may include microelectronics, sensors and surveillance devices.

Microsystems packaging requires the assembly and interconnections of microelectronics, MEMS, photonics, fluids and other microscale devices onto a system-level board or chip to form an integrated microsystems product. Because the microsystem package provides environmental protection, thermal management, testing and power distribution, the packaging controls the microsystems performance, cost, size, and reliability.

The stacked wafer technology provides a heterogeneously integrated, ultra-miniaturized, high performing, robust and cost-effective microsystem package. This highly integrated microsystem package can be miniaturized both in volume and footprint and provides all of the needed system level functions.

Sandia seeks to transfer technology for the benefit of the US industry. It is anticipated that commercial licenses may grant rights on a competitive basis to qualified interested parties for appropriate consideration. Licensing options may include grants for defined fields of use, non-exclusive rights, exclusive, or sublicensing rights.

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Keywords: microsystem, microelectronics, microscale, packaging, heterogeneous, wafer, integrated, thermal management, power distribution, miniature, robust, stacked, chip, protection, dielectric